

OPTION TABLE

PART No.	NOTCH AREA METALLIZED
1	WITH METALLIZATION
2	WITHOUT METALLIZATION

NOTES:

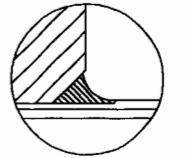
1. PLATING THICKNESS TO BE PER CUSTOMER'S SPECIFICATION.
2. SEAL AREA TO BE METALLIZED.
3. DIE ATTACH AREA TO BE METALLIZED.
4. SEAL RING AND DIE ATTACH PAD TO BE FLOATING FROM ANY LEADS.
5. LEAD RESISTANCE :0.30Ω MAX.
6. WIRE BOND PAD CONNECTED TO CORRESPONDED OUTER LEAD.
7. MISALIGNMENT OF METALLIZATION PATTERN IN CAVITY SHALL BE ACCEPTED DUE TO LAYER MISALIGNMENT.

MODIFICATION	DESCRIPTION	DATE	DRAWN	CHECKED	APPROVED
△	DELETED : VENDOR'S OPTION.				
△	ADDED : PART No.2 AND NOTE 6.7.	AUG.02.'07	S.NI	TO.H/M.SU	H.SA
	ADDED : SHEET(2/2)				
△	REDRAWN : CONVERTED CAD DATA	OCT.22.'98	Y.MI	SH.K/S.F	T.A
	CHANGED				

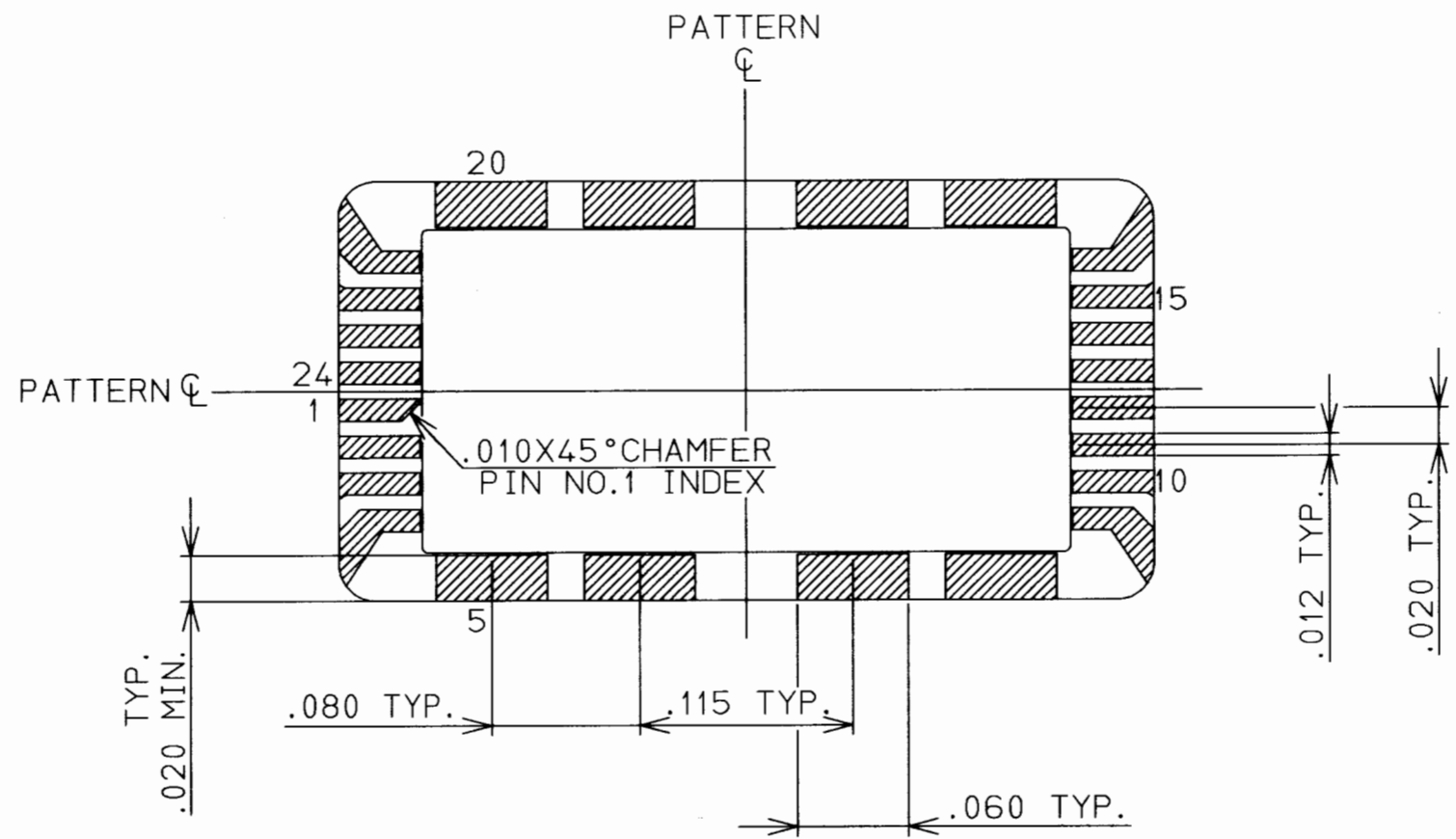
NAME 24 LEAD SIDE BRAZED PACKAGE  
 SCALE 5 / 1  
 MATERIAL AS INDICATED  
 KYOCERA

TOLERANCE UNLESS OTHERWISE SPECIFIED ±.005  
 THIRD ANGLE PROJECTION

SB024K160-2		S=0
SB024K160-1		D=0
DRAWN	CHECKED	APPROVED
H.K	K.M	
DRAWING NO. KD-80160-D		SHEET 1/2



DETAIL-A



BONDING PATTERN

MODIFICATION						NAME	TOLERANCE	DRAWN	CHECKED	APPROVED	DATE
						24 LEAD SIDE BRAZED PACKAGE	UNLESS OTHERWISE SPECIFIED	Y.M	SH.K/S.F	T.A	OCT.22.'98
						SCALE 10 / 1	MATERIAL				
							THIRD ANGLE PROJECTION				
	CHANGED	DATE	DRAWN	CHECKED	APPROVED		KYOCERA CORPORATION KYOTO JAPAN	DRAWING NO.			SHEET
								KD-80160-D			2/2